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TITLE : SOLDER ALLOY

ABSTRACT : PURPOSE: To provide a solder alloy which can improve the thermal stress resistance while guaranteeing the workability for soldering by adding inexpensive metals of Bi, Cu, Sb, etc., within a specific range to a Sn-Pb base solder, in the case of soldering parts for an electronic circuit on a printed circuit board with the flow method.

CONSTITUTION: This solder alloy consists of, by weight, 50 to 70% Sn, 0.1 to 2.0% Bi, 0.03 to 0.3% Cu, 0.1 to 2.0% Sb, and the balance pb, further this composition 100 weight part can be also added with 0.002 to 0.5 weight part P.

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